Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM}	50	V
Average Rectified Output Current	Io	15	A
Non-Repetitive Peak Forward Surge Current 8.3mS Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	290	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 6)	$R_{\theta JA}$	101	°C/W
Typical Thermal Resistance Junction to Ambient (Note 7)	$R_{\theta JA}$	20	°C/W
Typical Thermal Resistance Junction to Lead (Notes 7 & 8)	$R_{\theta JL}$	4	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V_F	— — — —	— 0.310 0.410 0.365	0.44 — 0.47 —	V	I_F =10A, T_J = +25°C I_F =10A, T_J = +125°C I_F =15A, T_J = +25°C I_F =15A, T_J = +125°C
Leakage Current (Note 9)	I_R	— — — —	0.08 0.17 3.5 35	0.3 0.5 — 105	mA	V_R = 30V , T_J = +25°C V_R = 50V , T_J = +25°C V_R = 30V , T_J = +85°C V_R = 50V , T_J = +125°C
Junction Capacitance	C_J	—	440	—	pF	V_R = 25V , T_J = +25°C

Notes:
6. FR-4 PCB, 2oz. Copper, minimum recommended pad layout per http://www.diodes.com.
7. Aluminum substrate PCB with 30mm x 30mm, full of 2oz. Copper pad and additional heatsink 42mm x 20mm x 12mm.
8. Junction to Lead (Cathode Terminal)
9. Short duration pulse test used to minimize self-heating effect.

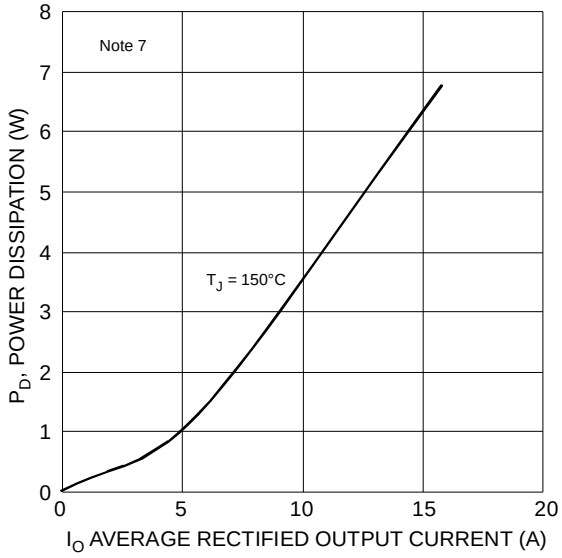


Figure 1 Forward Power Dissipation

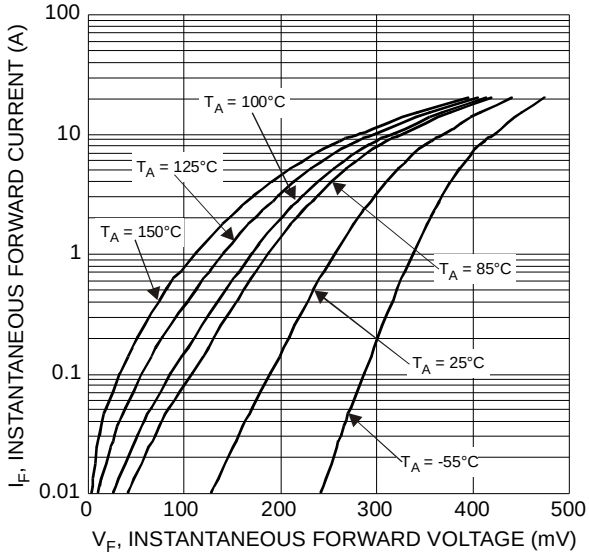


Figure 2 Typical Forward Characteristics

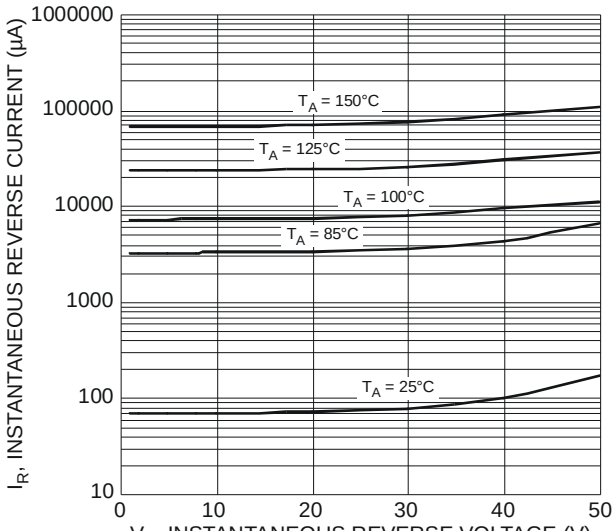


Figure 3 Typical Reverse Characteristics

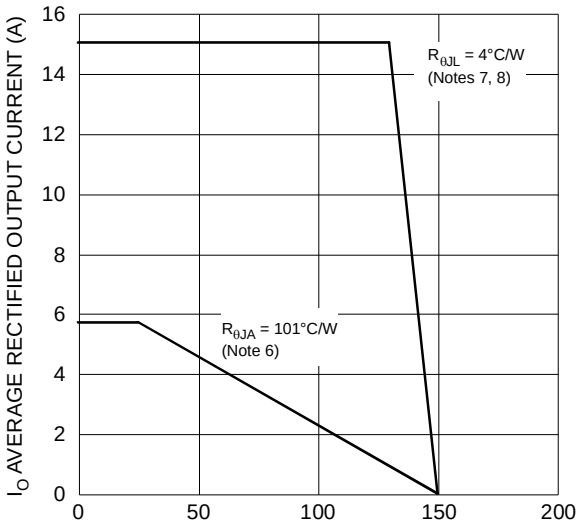


Figure 4 Forward Current Derating Curve

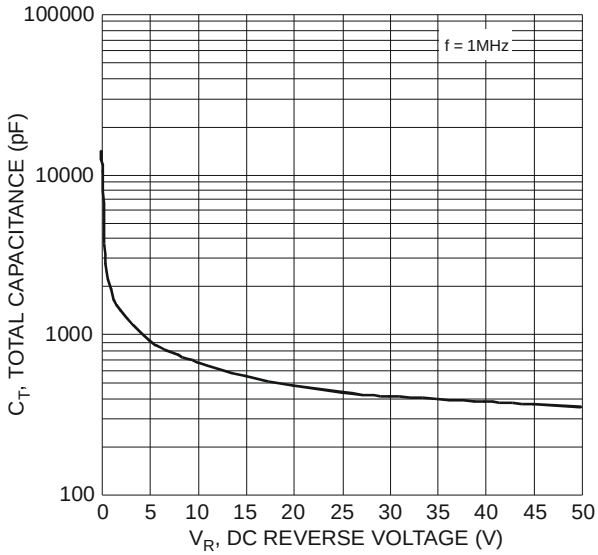
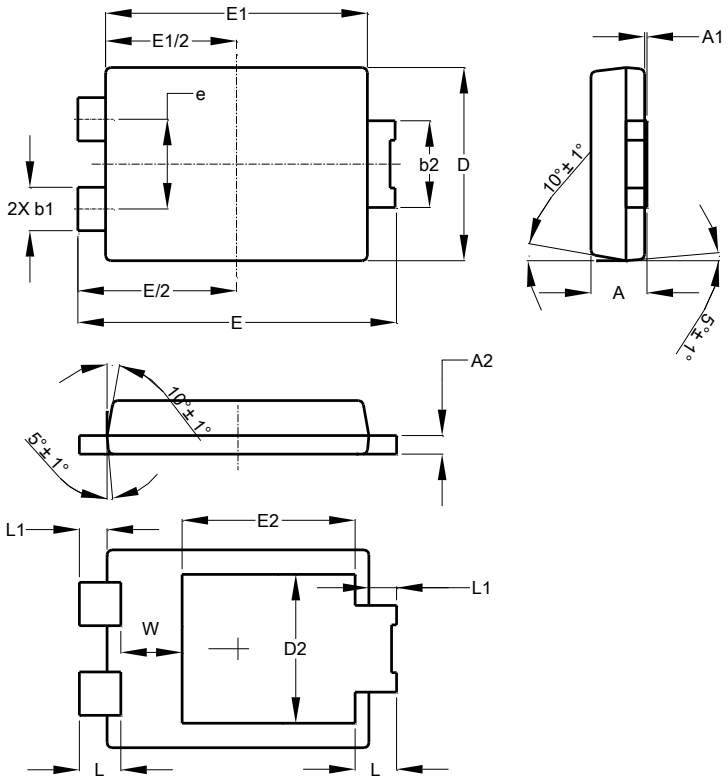


Figure 5 Total Capacitance vs. Reverse Voltage

Package Outline Dimensions

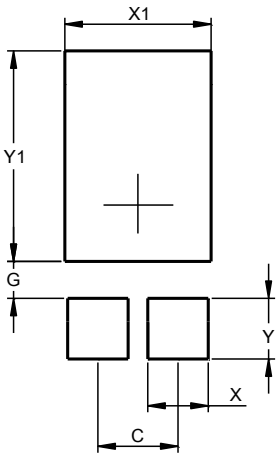
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



POWERDI®5			
Dim	**Min**	**Max**	**Typ**
A	1.05	1.15	1.10
A1	0.00	0.05	--
A2	0.33	0.43	0.381
b1	0.80	0.99	0.89
b2	1.70	1.88	1.78
D	3.90	4.05	3.966
D2	--	--	3.054
E	6.40	6.60	6.504
e	--	--	1.84
E1	5.30	5.45	5.37
E2	--	--	3.549
L	0.75	0.95	0.85
L1	0.50	0.65	0.57
W	1.10	1.41	1.255
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
C	1.840
G	0.852
X	1.390
X1	3.360
Y	1.400
Y1	4.860

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